

# CD4028B Types

## BCD-to-Decimal Decoder

### High-Voltage Types (20-Volt Rating)

■ CD4028B types are BCD-to-decimal or binary-to-octal decoders consisting of buffering on all 4 inputs, decoding logic gates, and 10 output buffers. A BCD code applied to the four inputs, A to D, results in a high level at the selected one of 10 decimal decoded outputs. Similarly, a 3-bit binary code applied to inputs A through C is decoded in octal code at output 0 to 7 if D = "0". High drive capability is provided at all outputs to enhance dc and dynamic performance in high fan-out applications.

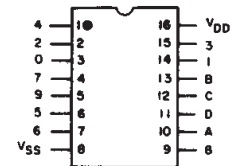
The CD4028B-Series types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

### Features:

- BCD-to-decimal decoding or binary-to-octal decoding
- High decoded output drive capability
- "Positive logic" inputs and outputs. . . . . decoded outputs go high on selection
- Medium-speed operation. . . . .
- $t_{PHL}, t_{PLH} = 80 \text{ ns (typ.) @ } V_{DD} = 10 \text{ V}$
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1  $\mu\text{A}$  at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range):
  - 1 V at  $V_{DD} = 5 \text{ V}$
  - 2 V at  $V_{DD} = 10 \text{ V}$
  - 2.5 V at  $V_{DD} = 15 \text{ V}$
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications:

- Code conversion
- Indicator-tube decoder
- Address decoding—memory selection control



Top View  
TERMINAL DIAGRAM

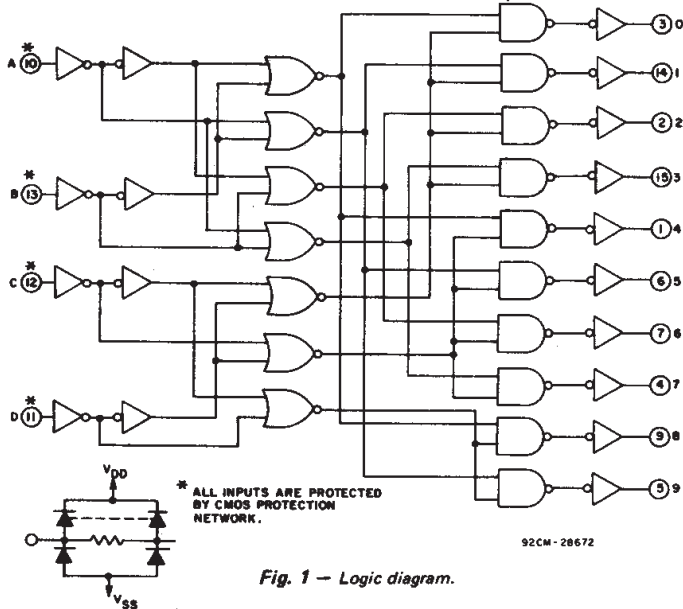


Fig. 1 - Logic diagram.

TABLE I - TRUTH TABLE

D	C	B	A	0	1	2	3	4	5	6	7	8	9
0	0	0	0	1	0	0	0	0	0	0	0	0	0
0	0	0	1	0	1	0	0	0	0	0	0	0	0
0	0	1	0	0	0	1	0	0	0	0	0	0	0
0	0	1	1	0	0	0	1	0	0	0	0	0	0
0	1	0	0	0	0	0	0	1	0	0	0	0	0
0	1	0	1	0	0	0	0	0	1	0	0	0	0
0	1	1	0	0	0	0	0	0	0	1	0	0	0
0	1	1	1	0	0	0	0	0	0	0	1	0	0
1	0	0	0	0	0	0	0	0	0	0	0	1	0
1	0	0	1	0	0	0	0	0	0	0	0	0	1
1	0	1	0	0	0	0	0	0	0	0	0	0	0
1	0	1	1	0	0	0	0	0	0	0	0	0	0
1	1	0	0	0	0	0	0	0	0	0	0	0	0
1	1	0	1	0	0	0	0	0	0	0	0	0	0
1	1	1	0	0	0	0	0	0	0	0	0	0	0
1	1	1	1	0	0	0	0	0	0	0	0	0	0

I = HIGH LEVEL      0 = LOW LEVEL

### MAXIMUM RATINGS, Absolute-Maximum Values:

- DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )  
Voltages referenced to  $V_{SS}$  Terminal) ..... -0.5V to +20V
- INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to  $V_{DD} + 0.5\text{V}$
- DC INPUT CURRENT, ANY ONE INPUT .....  $\pm 10\text{mA}$
- POWER DISSIPATION PER PACKAGE ( $P_D$ ):  
For  $T_A = -55^\circ\text{C}$  to  $+100^\circ\text{C}$  ..... 500mW  
For  $T_A = +100^\circ\text{C}$  to  $+125^\circ\text{C}$  ..... Derate Linearly at  $12\text{mW}/^\circ\text{C}$  to  $200\text{mW}$
- DEVICE DISSIPATION PER OUTPUT TRANSISTOR  
FOR  $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$  ..... 100mW
- OPERATING-TEMPERATURE RANGE ( $T_A$ ) .....  $-55^\circ\text{C}$  to  $+125^\circ\text{C}$
- STORAGE TEMPERATURE RANGE ( $T_{stg}$ ) .....  $-65^\circ\text{C}$  to  $+150^\circ\text{C}$
- LEAD TEMPERATURE (DURING SOLDERING):  
At distance  $1/16 \pm 1/32$  inch ( $1.59 \pm 0.79\text{mm}$ ) from case for 10s max .....  $+265^\circ\text{C}$

# CD4028B Types

## RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply Voltage Range (For $T_A$ = Full Package Temperature Range)	3	18	V

## STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	$V_O$ (V)	$V_{IN}$ (V)	$V_{DD}$ (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, $I_{DD}$ Max.	-	0.5	5	5	5	150	150	-	0.04	5	$\mu A$
	-	0.10	10	10	10	300	300	-	0.04	10	
	-	0.15	15	20	20	600	600	-	0.04	20	
	-	0.20	20	100	100	3000	3000	-	0.08	100	
Output Low (Sink) Current $I_{OL}$ Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, $I_{OH}$ Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	1	-	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage: Low-Level, $V_{OL}$ Max.	-	0.5	5	0.05				-	0	0.05	V
	-	0.10	10	0.05				-	0	0.05	
	-	0.15	15	0.05				-	0	0.05	
Output Voltage: High-Level, $V_{OH}$ Min.	-	0.5	5	4.95				4.95	5	-	V
	-	0.10	10	9.95				9.95	10	-	
	-	0.15	15	14.95				14.95	15	-	
Input Low Voltage, $V_{IL}$ Max.	0.5, 4.5	-	5	1.5				-	-	1.5	V
	1.9	-	10	3				-	-	3	
	1.5, 13.5	-	15	4				-	-	4	
Input High Voltage, $V_{IH}$ Min.	0.5, 4.5	-	5	3.5				3.5	-	-	V
	1.9	-	10	7				7	-	-	
	1.5, 13.5	-	15	11				11	-	-	
Input Current $I_{IN}$ Max.	-	0.18	18	$\pm 0.1$	$\pm 0.1$	$\pm 1$	$\pm 1$	-	$\pm 10^{-5}$	$\pm 0.1$	$\mu A$

DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = 25^\circ C$ ,  $C_L = 50$  pF, Input  $t_r, t_f = 20$  ns,  $R_L = 200$  k $\Omega$

CHARACTERISTIC	TEST CONDITIONS	LIMITS		UNITS
	$V_{DD}$ (V)	Typ.	Max.	
Propagation Delay Time: $t_{PHL}, t_{PLH}$	5	175	350	ns
	10	80	160	
	15	60	120	
Transition Time $t_{THL}, t_{TLH}$	5	100	200	ns
	10	50	100	
	15	40	80	
Input Capacitance, $C_{IN}$	-	5	7.5	pF



Fig. 2 - Typical output low (sink) current characteristics.

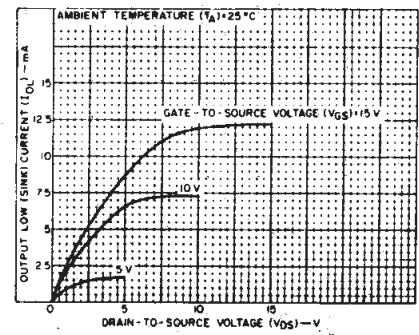


Fig. 3 - Minimum output low (sink) current characteristics.



Fig. 4 - Typical propagation delay time as a function of load capacitance.

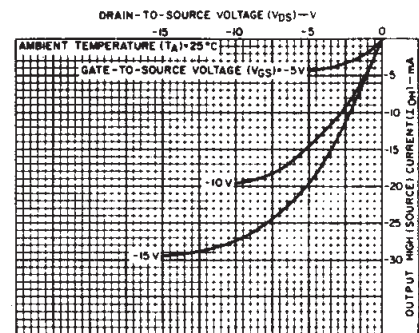


Fig. 5 - Typical output high (source) current characteristics.

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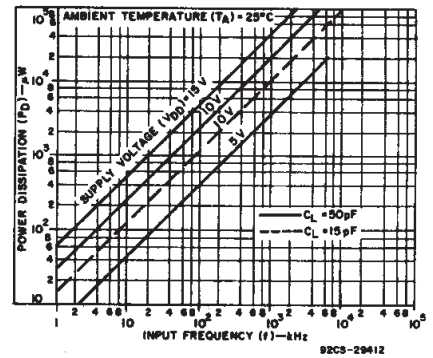
# CD4028B Types

**TABLE II – CODE CONVERSION CHART**

INPUTS				INPUT CODES					OUTPUT NUMBER																	
				Hexa-Decimal		Decimal																				
D	C	B	A	4-BIT BINARY	4-BIT GRAY	EXCESS-3	EXCESS-3 GRAY	AIKEN	4-2-2-1	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	
0	0	0	0	0	0					0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1					1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0
0	0	1	0	2	3			0	2	2		0	0	1	0	0	0	0	0	0	0	0	0	0	0	0
0	0	1	1	3	2			0	3	3		0	0	0	1	0	0	0	0	0	0	0	0	0	0	0
0	1	0	0	4	7			1	4	4		0	0	0	0	1	0	0	0	0	0	0	0	0	0	0
0	1	0	1	5	6			2				3	0	0	0	0	0	1	0	0	0	0	0	0	0	0
0	1	1	0	6	4			3	1			4	0	0	0	0	0	0	1	0	0	0	0	0	0	0
0	1	1	1	7	5			4	2			5	0	0	0	0	0	0	1	0	0	0	0	0	0	0
1	0	0	0	8	15			5				6	0	0	0	0	0	0	0	1	0	0	0	0	0	0
1	0	0	1	9	14			6				7	0	0	0	0	0	0	0	0	1	0	0	0	0	0
1	0	1	0	10	12			7	9			8	0	0	0	0	0	0	0	0	0	1	0	0	0	0
1	0	1	1	11	13			8				9	0	0	0	0	0	0	0	0	0	0	1	0	0	0
1	1	0	0	12	8			9	5			10	0	0	0	0	0	0	0	0	0	0	0	1	0	0
1	1	0	1	13	9			10	6			11	0	0	0	0	0	0	0	0	0	0	0	0	1	0
1	1	1	0	14	11			11	7			12	0	0	0	0	0	0	0	0	0	0	0	0	0	1
1	1	1	1	15	10			12	8			13	0	0	0	0	0	0	0	0	0	0	0	0	0	1



**Fig. 6 – Minimum output high (source) current characteristics.**



**Fig. 7 – Typical dynamic power dissipation as a function of input frequency.**



**Fig. 8 – Typical transition time as a function of load capacitance.**



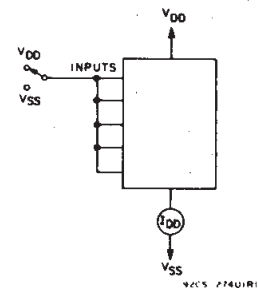
**Fig. 9 – Input current test circuit.**



**Fig. 11 – Input voltage test circuit.**



**Fig. 10 – Dynamic power dissipation test circuit.**



**Fig. 12 – Quiescent device current test circuit.**

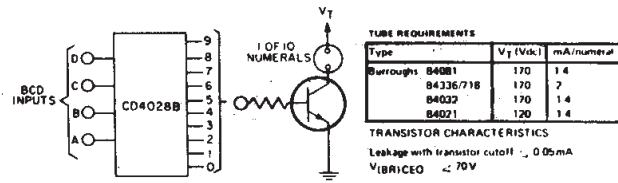
## TYPICAL APPLICATIONS



**Fig. 13 – Code conversion circuit.**

The circuit shown in Fig. 13 converts any 4-bit code to a decimal or hexadecimal code. Table 2 shows a number of codes and the decimal or hexadecimal number in these codes which must be applied to the input terminals of the CD4028B to select a particular output. For example: in order to get a high on output No. 8 the input must be either an 8 expressed in 4-Bit Binary code, a 15 expressed in 4-Bit Gray code, or a 5 expressed in Excess-3 code.

# CD4028B Types



^(Trademark) Burroughs Corp.

92CS-29413

Fig. 14 — Neon readout (Nixie Tube<sup>^</sup>) display application.

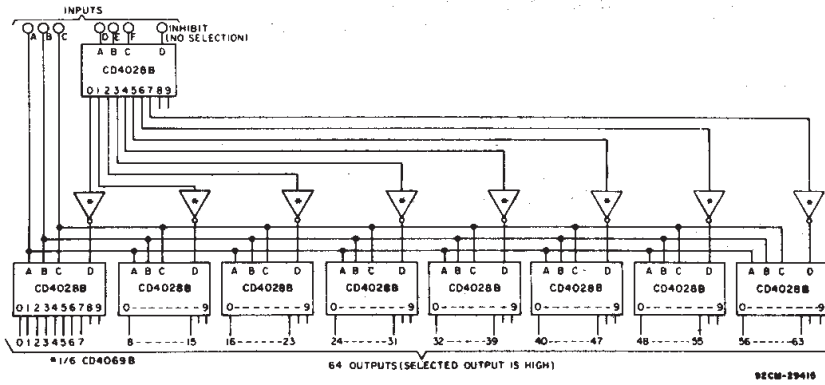
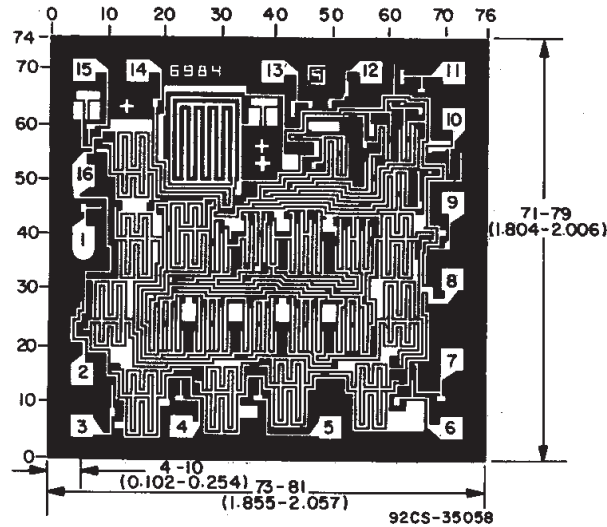


Fig. 15 — 6-bit binary to 1-of-64 address decoder.



## CD4028BH DIMENSIONS AND PAD LAYOUT

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).

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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD4028BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4028BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4028BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD4028BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD4028BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4028BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4028BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4028BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4028BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4028BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4028BNSR	SO	NS	16	2000	367.0	367.0	38.0
CD4028BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0



J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

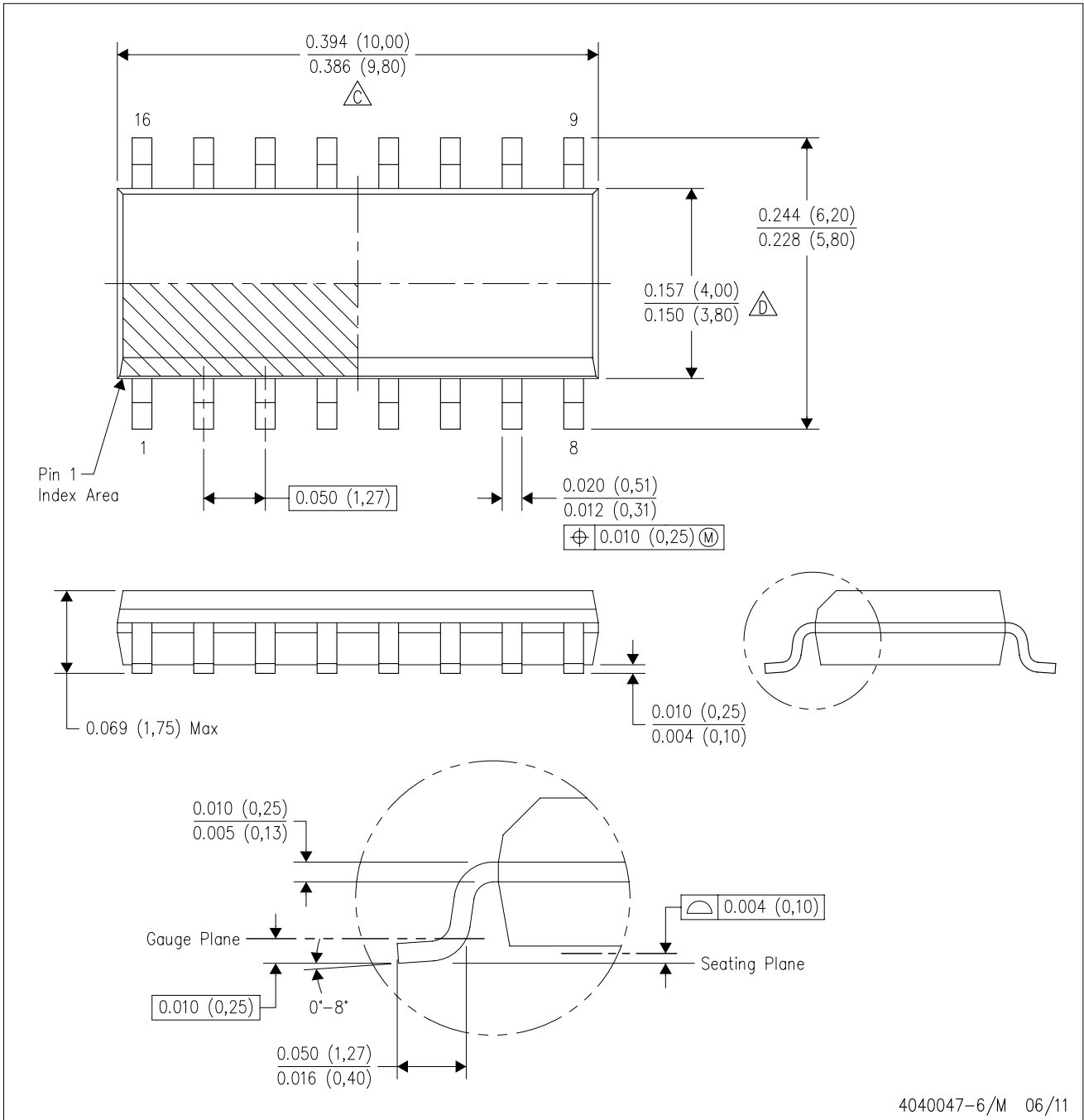
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - (C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - (D) The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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